

## AMENDMENTS TO THE CLAIMS

**1. (Currently Amended)** A prepreg for a printed wiring board material comprising a thermosetting resin (D) composition containing, as an essential component, an aluminum hydroxide-boehmite composite (A) obtained by hydrothermal treatment of aluminum hydroxide, boehmite (B), and a substrate (I), wherein the weight ratio of the aluminum hydroxide-boehmite composite (A) to boehmite (B) is in the range of from 45:55 to 95:5, and the weight ratio of aluminum hydroxide to boehmite in the aluminum hydroxide-boehmite composite (A) is in the range of from 45:55 to 95:5.

**2. (Canceled)**

**3. (Currently Amended)** A The prepreg according to claim 1, wherein the amount of the aluminum hydroxide-boehmite composite (A) per 100 parts by weight of the thermosetting resin (D) is 1 to 200 parts by weight.

**4. (Currently Amended)** A The prepreg according to claim 1, wherein the thermosetting resin (D) composition further contains a silane coupling agent (E)~~or a wetting dispersing agent (F).~~

**5. (Canceled)**

**6. (Canceled)**

**7. (Canceled)**

**8. (Currently Amended)** A The prepreg according to claim 1, wherein the thermosetting resin (D) contains a cyanate ester resin (G) or a nonhalogenated epoxy resin (H).

**9. (Currently Amended)** A The prepreg according to claim 8,

wherein the cyanate ester resin (G) is 2,2-bis(4-cyanatophenyl)propane, cyanates obtained by a reaction between novolak and cyan halide, or a mixture of these.

**10. (Currently Amended)** A The prepreg according to claim 8,

wherein the nonhalogenated epoxy resin (H) is one member or at least two members selected from the group consisting of a bisphenol F type epoxy resin, a phenol novolak type epoxy resin, a cresol novolak type epoxy resin, a polyfunctional phenol type epoxy resin, a naphthalene type epoxy resin, a biphenyl novolak type epoxy resin and a phosphorus-containing epoxy resin.

**11. (Original)** A laminate obtained by stacking the prepreg as recited in claim 1.

**12. (Original)** A metal-foil-clad laminate obtained by bonding metal foil(s) to one surface or both surfaces of the laminate as recited in claim 11.

**13. (New)** The prepreg according to claim 1,

wherein the thermosetting resin (D) composition further contains a wetting dispersing agent (F).